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(54) **ELECTRONIC ELEMENT HOUSING
PACKAGE AND ELECTRONIC APPARATUS**

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(57) **ABSTRACT**

An electronic element housing package includes a bottom substrate, a bank portion, and a conductor part, in which the bottom substrate and the bank portion are an integrated object made of ceramic, the bottom substrate includes a region surrounded by the bank portion as a mounting portion for mounting an electronic element, the conductor part includes a first conductor, a second conductor, and a third conductor, the first conductor is partially exposed on a mounting surface of the bottom substrate and embedded in the bottom substrate, at least a part of the third conductor is disposed on an upper surface of the bank portion and a part thereof is exposed, and the second conductor is present between the first conductor and the third conductor inside the bottom substrate and the bank portion and electrically connects the first conductor and the third conductor.

